

JAPANESE PATENT OFFICE
PATENT JOURNAL
KOKAI PATENT APPLICATION NO. HEI 2[1990]-129955

Int. Cl. ⁵ :	H 01 L 25/04 25/18 H 05 K 1/18 H 01 L 25/04
Sequence Nos. for Office Use:	6736-5E 7638-5F
Application No.:	Sho 63[1988]-282815
Application Date:	November 9, 1988
Publication Date:	May 18, 1990
No. of Claims:	1 (Total of 4 pages)
Examination Request:	Not requested

SEMICONDUCTOR CHIP PACKAGING STRUCTURE

Inventors:	Masaaki Ukita Sanjo Plant, Shimazu Seisakusho, 1 Kuwabara-cho, Nishinokyo, Nakagyo-ku, Kyoto-shi, Kyoto-fu Satoshi Hirooka Sanjo Plant, Shimazu Seisakusho, 1 Kuwabara-cho, Nishinokyo, Nakagyo-ku, Kyoto-shi, Kyoto-fu
------------	--

Applicant:

Shimazu Seisakusho,
1 Kuwabara-cho,
Nishinokyo, Nakagyo-ku,
Kyoto-shi, Kyoto-fu

Agent:

Shin Nishida, patent
attorney

[There are no amendments to this patent.]

Claim

Semiconductor chip packaging structure wherein part of a group of electrodes formed on one surface of a first semiconductor chip is directly connected electrically and mechanically to a pad formed on a surface near one end of a circuit board, with the rest of the electrodes on this first semiconductor chip projecting beyond the aforementioned end relative to the aforementioned circuit board and an electrode formed on a second semiconductor chip being directly connected electrically and mechanically to the rest of the electrodes.

* * *